

Description

The AL1696 is a highly integrated high power factor constant current converter for mains dimmable LED driver applications. The AL1696 controls the system operating in boundary conduction mode (BCM) for ease in EMI/EMC qualification and testing to meet the latest regulatory standards.

The AL1696 with built-in MOSFET solution reduces the bill of material (BOM) cost by eliminating the need of auxiliary winding and external high-voltage MOSFET.

The AL1696 can be compatible with a wide range of dimmers including leading edge and trailing edge dimmers. Some dimmers can achieve deep dimming down to 1%. The AL1696 dimming curve is compliant with the standard of NEMA SSL6.

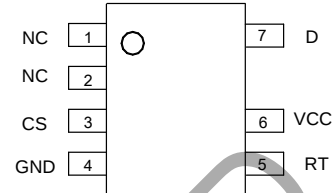
The AL1696 is available in SO-7 package, which provides an extra pin spacing between the high-voltage MOSFET's drain and low-voltage pins to increase electricity isolation.

Features

- Internal MOSFET up to 300V/3A, 400V/3A, 500V/2A, 600V/2A
- Tight Current Sense Tolerance: $\pm 3\%$
- Low Startup Current: 150 μ A
- Low Operation Current: 120 μ A (Switching Frequency at 5kHz)
- Single Winding Inductor
- Wide Range of Dimmer Compatibility
- Dimming Curve Compliant with NEMA SSL6
- Internal Protections
 - Undervoltage Lockout (UVLO)
 - Leading-Edge Blanking (LEB)
 - Cycle-by-Cycle Overcurrent Protection (OCP)
 - Output Short Protection (OSP)
 - Overtemperature Protection (OTP)
- SO-7 Package
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please [contact us](#) or your local Diodes representative.**
<https://www.diodes.com/quality/product-definitions/>

Pin Assignments

(Top View)



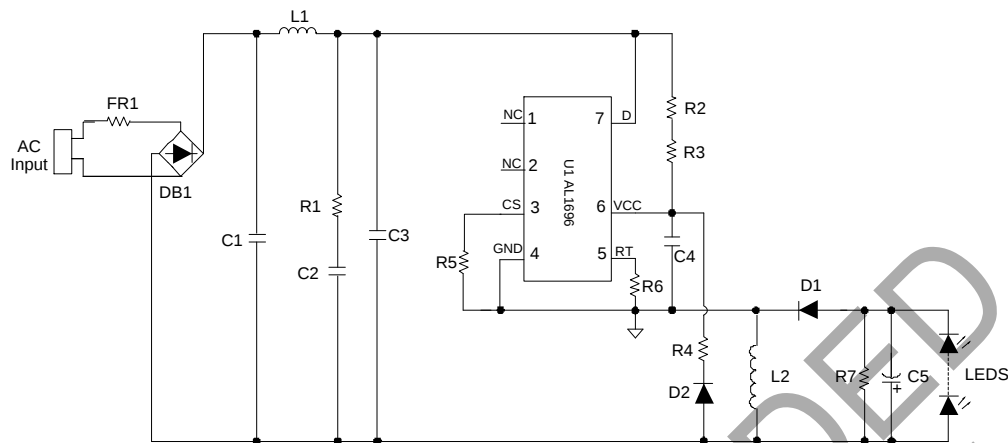
SO-7

Applications

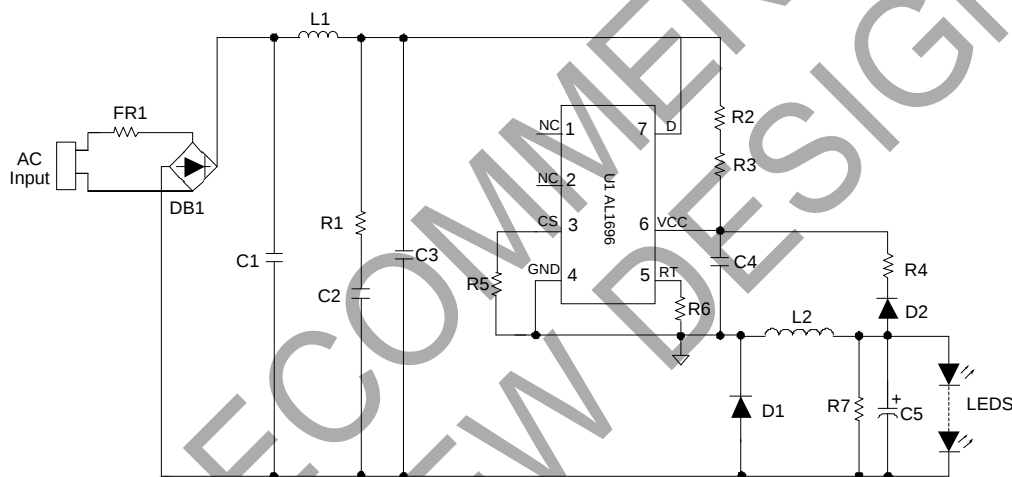
- Mains dimmable LED lamps
- Offline LED power supply drivers

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
 2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

Typical Applications Circuit



Buck-Boost Application Circuit

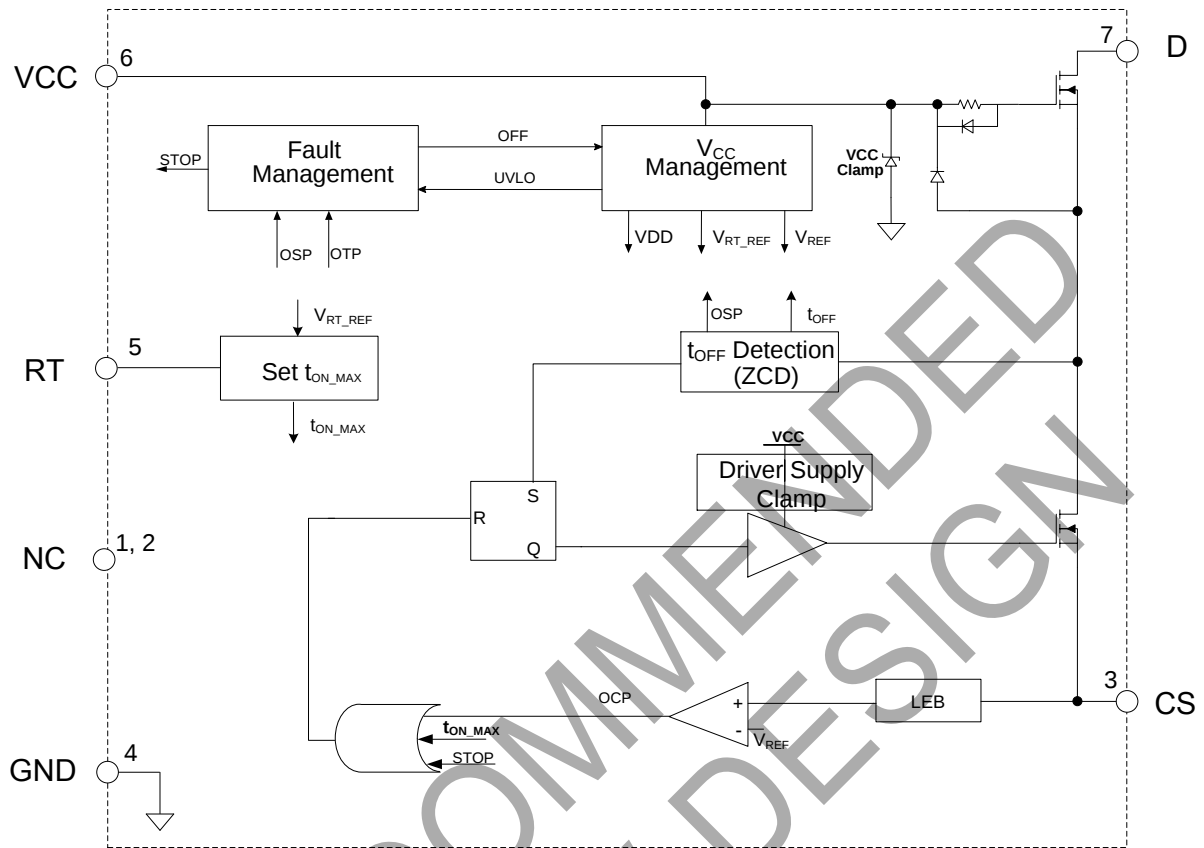


Buck Application Circuit

Pin Descriptions

Pin Number	Pin Name	Function
1, 2	NC	No connection
3	CS	Current sensing
4	GND	Ground
5	RT	Resistor set the system's maximum t_{ON}
6	VCC	Power supply voltage
7	D	Drain of the internal high-voltage MOSFET

Functional Block Diagram



Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.) (Note 4)

Symbol	Parameter	Rating	Unit
V _{CC}	Power Supply Voltage	18	V
V _D	Voltage on D Pin (AL1696-30AS7-13)	300	V
	Voltage on D Pin (AL1696-30BAS7-13)	400	V
	Voltage on D Pin (AL1696-20BS7-13)	500	V
	Voltage on D Pin (AL1696-20CS7-13)	600	V
I _D	Continuous Drain Current T _C = +25°C (AL1696-30AS7-13)	3.0	A
	Continuous Drain Current T _C = +25°C (AL1696-30BAS7-13)	3.0	A
	Continuous Drain Current T _C = +25°C (AL1696-20BS7-13)	2.0	A
	Continuous Drain Current T _C = +25°C (AL1696-20CS7-13)	2.0	A
V _{CS}	Voltage on CS Pin	-0.3 to 7	V
V _{RT}	Voltage on RT Pin	-0.3 to 7	V
T _J	Operating Junction Temperature	-40 to +150	°C
T _{STG}	Storage Temperature	-65 to +150	°C
T _{LEAD}	Lead Temperature (Soldering, 10 seconds)	+260	°C
P _D	Power Dissipation and Thermal Characteristics (T _A = +50°C)	0.8	W
θ _{JA}	Thermal Resistance (Junction to Ambient) (Note 5)	123	°C/W
θ _{JC}	Thermal Resistance (Junction to Case) (Note 5)	19	°C/W
—	ESD (Human Body Model)	2,000	V
	ESD (Machine Model)	200	V

Notes: 4. Stresses greater than those listed under *Absolute Maximum Ratings* can cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to *Absolute Maximum Ratings* for extended periods can affect device reliability.
5. Device mounted on 1" x 1" FR-4 substrate PCB, 2oz copper, with minimum recommended pad layout.

Recommended Operating Conditions (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Min	Max	Unit
T _A (Note 6)	Ambient Temperature	-40	+105	°C

Note: 6. The device can operate normally at +125°C ambient temperature under the condition that the junction temperature is less than +150°C.

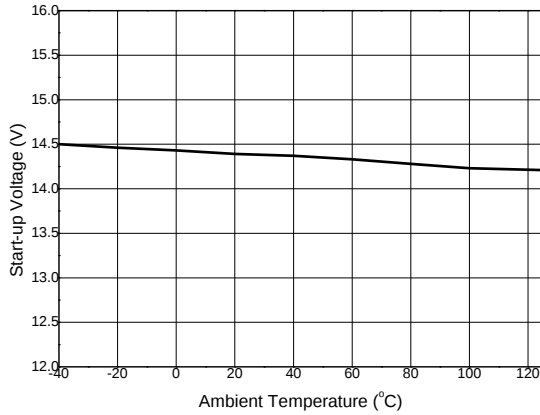
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
UVLO						
V _{TH(ST)}	Startup Voltage	—	—	14.5	—	V
V _{OPR(MIN)}	Minimal Operating Voltage	After Turn On	—	8.5	—	V
V _{CC_CLAMP}	V _{CC} Clamp Voltage	I _{CC} = 1mA	—	16	—	V
Standby Current						
I _{ST}	Startup Current	V _{CC} = V _{TH(ST)} -0.5V Before Startup	—	150	—	μA
I _{CC(OPR)}	Operating Current	Switching Frequency at 5kHz	—	120	—	μA
Internal High-Voltage MOSFET						
R _{DS(ON)}	Drain-Source On-State Resistance	AL1696-30A	—	—	3	Ω
		AL1696-30BA	—	—	3.4	Ω
		AL1696-20B	—	—	6	Ω
		AL1696-20C	—	—	5.5	Ω
I _{DS}	Continuous Drain-Source Current	AL1696-30A	—	—	3.0	A
		AL1696-30BA	—	—	3.0	A
		AL1696-20B	—	—	2.0	A
		AL1696-20C	—	—	2.0	A
V _{DS}	Drain-Source Breakdown Voltage	AL1696-30A	300	—	—	V
		AL1696-30BA	400	—	—	V
		AL1696-20B	500	—	—	V
		AL1696-20C	600	—	—	V
I _{DSS}	Drain-Source Leakage Current	AL1696-30A @V _{DS} = 300V, V _{GS} = 0V	—	—	1	μA
		AL1696-30BA @V _{DS} = 400V, V _{GS} = 0V	—	—	1	μA
		AL1696-20B @V _{DS} = 500V, V _{GS} = 0V	—	—	1	μA
		AL1696-20C @V _{DS} = 600V, V _{GS} = 0V	—	—	1	μA
RT						
V _{RT}	Reference Voltage of RT Pin	—	—	0.5	—	V
Current Sense						
V _{REF}	Current Sense Reference	—	0.388	0.400	0.412	V
t _{ON_MIN}	Minimum t _{ON}	—	—	550	—	ns
t _{ON_MAX}	Maximum t _{ON}	R _T = 27kΩ	—	8	—	μs
t _{OFF_MAX}	Maximum t _{OFF}	—	—	180	—	μs
t _{OFF_MIN}	Minimum t _{OFF} (Note 7)	—	—	6	—	μs
Overtemperature Protection						
—	Shutdown Temperature (Notes 7 & 8)	—	—	+170	—	°C

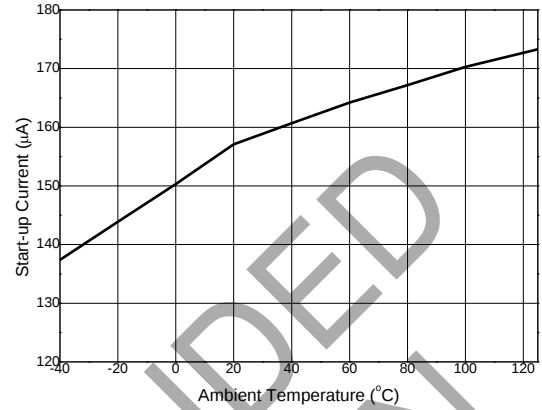
Notes: 7. These parameters, although guaranteed by design, are not 100% tested in production.
 8. The device will latch when OTP happens and the device will not operate constantly at this temperature.

Performance Characteristics (Note 9)

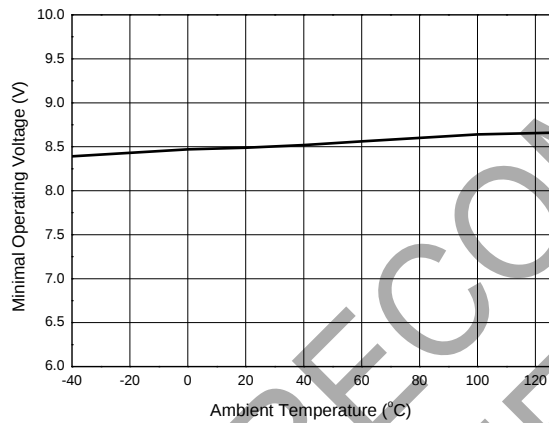
Startup Voltage vs. Ambient Temperature



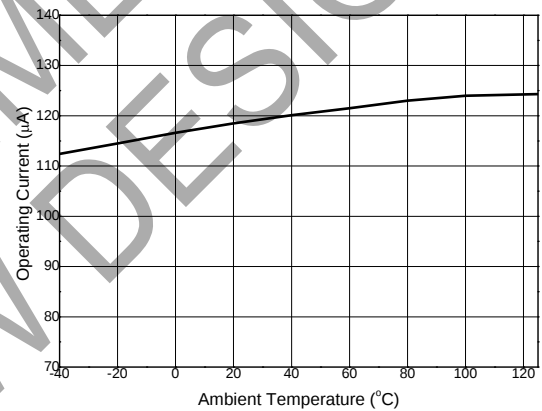
Startup Current vs. Ambient Temperature



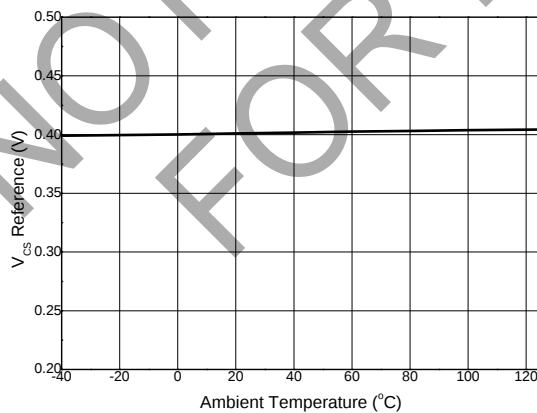
Minimal Operating Voltage vs. Ambient Temperature



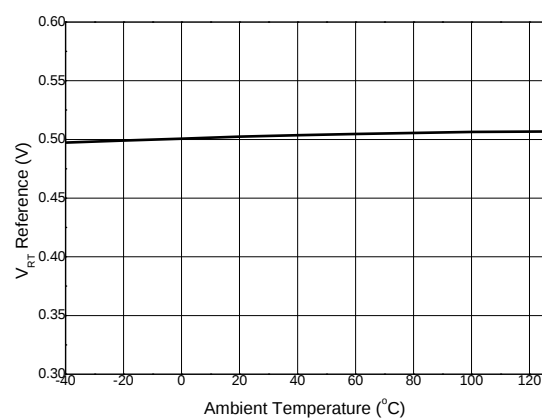
Operating Current vs. Ambient Temperature



V_{CS} Reference vs. Ambient Temperature



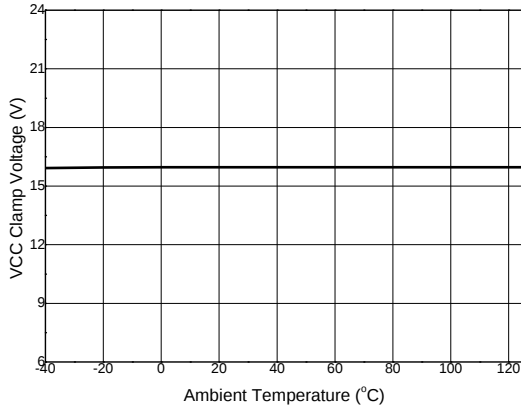
V_{RT} Reference vs. Ambient Temperature



Note: 9. These electrical characteristics are tested under DC condition. The ambient temperature is equal to the junction temperature of the device.

Performance Characteristics (continued) (Note 9)

VCC Clamp Voltage vs. Ambient Temperature



Note: 9. These electrical characteristics are tested under DC condition. The ambient temperature is equal to the junction temperature of the device.

NOT RECOMMENDED
FOR NEW DESIGN

Converter Operation

The AL1696 internal MOSFET's on time is limited by t_{ON_MAX} which is set through RT pin and internal 0.4V reference. The MOSFET will be turned off either its on-time triggers t_{ON_MAX} or input voltage on CS pin triggers internal 0.4V reference voltage. So if the t_{ON_MAX} is set to a very small value, the system will operate in constant on-time (t_{ON_MAX}) mode during the whole rectified mains cycle. It will result in a good power factor, but the line regulation will be worse. Normally, a recommended t_{ON_MAX} should make the system operate in constant on-time (t_{ON_MAX}) mode at valley of input voltage and peak current mode at the crest. A trade-off between PF and line regulation need to be done when setting t_{ON_MAX} .

Figure 1. Typical Buck-Boost Application Circuit

During startup, the VCC capacitor C4 is charged through startup resistors (R2, R3) from the rectified mains input until the startup voltage is reached, the AL1696 starts switching. In normal operation, the VCC supply is provided from two paths: one is from startup resistors (R2, R3) and the other is from output voltage (V_{OUT}) through one diode (D2). In this way the system can provide sufficient VCC supply at low dimming angle.

When VCC voltage drops below the undervoltage lockout (UVLO), IC will stop switching. The IC will restart once the voltage on VCC pin exceeds the startup voltage ($V_{TH(ST)}$) again.

Undervoltage Lockout (UVLO)

Leading-Edge Blanking (LEB)

To prevent false detection of the peak current through MOSFET, a blanking time following switch-on is designed. When the internal switch turns on, a short current spike may appear because of the discharge of the parasitic capacitor over MOSFET's drain and source. It will be ignored during the LEB time (t_{ON_MIN}).

Functional Description and Application Information (continued)

Cycle-by-Cycle Overcurrent Protection (OCP)

The AL1696 has a built-in peak current detector. The R5 connected to the CS pin is used to sense the current through MOSFET and will be one of the inputs. The detection circuit is activated after the LEB time. When the voltage on CS pin reaches V_{REF}, the IC will turn off the switch to limit the output current.

The peak current (I_{PEAK}) of the MOSFET can be set as below:

$$I_{PEAK} = \frac{V_{REF}}{R5}$$

It automatically provides a cycle-by-cycle protection of maximum current through MOSFET during operation. A propagation delay exists between over current detection and actual source-switch off, so the actual peak current will be a little higher than the OCP level set by R5.

Output-Short Protection (OSP)

When LED is shorted, the device cannot detect the t_{OFF} time, and the system will work with low switching frequency of 5kHz.

Overtemperature Protection (OTP)

The AL1696 has OTP protection function. When the junction temperature reaches +170°C typical, it will trigger an overtemperature protection which makes IC shut down and latched. Once OTP is triggered, the system will only restart after the system's power supply powers off and on again.

Design Parameters Based on Buck-Boost Topology

Setting the Current Sense Resistor R5

In AL1696 typical application, a t_{ON_MAX} is recommended to make the system operate at constant on-time (t_{ON_MAX}) mode at valley of input voltage and peak current mode at the crest. In most cases, the t_{ON_MAX} will set to be 1.3 times of the t_{ON} at crest, and the critical angle of two operation modes will be:

$$\theta = a \sin\left(\frac{1}{1.3}\right)$$

Then the output current can be calculated as below:

$$I_{O_MEAN} = \frac{V_{REF}}{2\pi \cdot R5} \left(\int_0^{\theta} 1.3 \cdot \sin(\theta) \frac{\sqrt{2}V_{IN_RMS} \sin(\theta)}{\sqrt{2}V_{IN_RMS} \sin(\theta) + V_O} dt + \int_{\theta}^{\pi-\theta} \frac{\sqrt{2}V_{IN_RMS} \sin(\theta)}{\sqrt{2}V_{IN_RMS} \sin(\theta) + V_O} dt + \int_{\pi-\theta}^{\pi} 1.3 \cdot \sin(\theta) \frac{\sqrt{2}V_{IN_RMS} \sin(\theta)}{\sqrt{2}V_{IN_RMS} \sin(\theta) + V_O} dt \right)$$

Where,

V_{REF} is the internal reference, typical 0.4V.

R5 is the current sense resistor.

V_{IN_RMS} is the input voltage's RMS value.

V_O is the system output voltage.

Inductance Selection (L2)

The peak current of the MOSFET is calculated as below:

$$I_{PEAK} = \frac{V_{REF}}{R5}$$

The AL1696 is operating in boundary conduction mode which results in a variable operating frequency. The minimum switching frequency f_{MIN} should be set at the crest of the minimum AC input voltage. Inductance should be calculated according to the chosen f_{MIN}:

$$L2 = \frac{\sqrt{2}V_{IN_RMS} \cdot V_O}{I_{PEAK} \cdot (\sqrt{2}V_{IN_RMS} + V_O) \cdot f_{MIN}}$$

Functional Description and Application information (continued)

According to the Faraday's Law of Induction, the winding number of the inductance can be calculated by:

$$N_{L2} = \frac{L2 \cdot I_{PEAK}}{A_e \cdot B_m}$$

Where,

A_e is the core effective area.

B_m is the maximum magnetic flux density.

ton_MAX Setting

In order to get a high-power-factor and good dimmer compatibility, the system should operate in constant on time mode at valley of input voltage. It can be realized by setting the maximum on time, which is set by an external resistor connected to RT pin.

And the t_{ON} time has the below equation:

$$t_{ON_MAX} = \frac{25 \cdot C_{REF} \cdot R6}{V_{RT_REF}}$$

Where,

V_{RT_REF} is the internal RT pin 0.5V's reference.

C_{REF} is the internal 6pF capacitor.

Dimmer Compatibility

Passive Bleeder Design

The passive bleeder is designed to supply latching and holding current to get rid of dimmer's misfire and flicker.

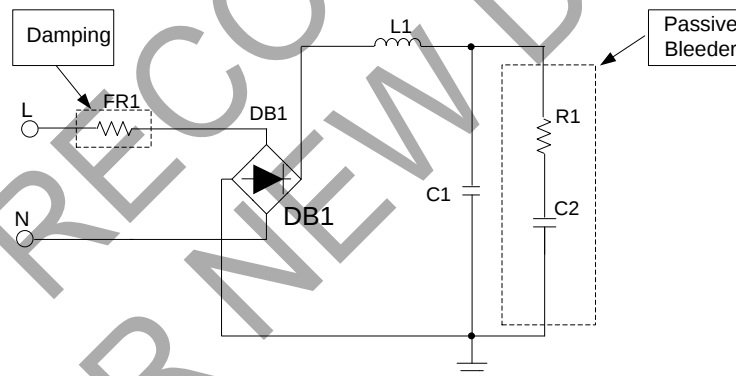


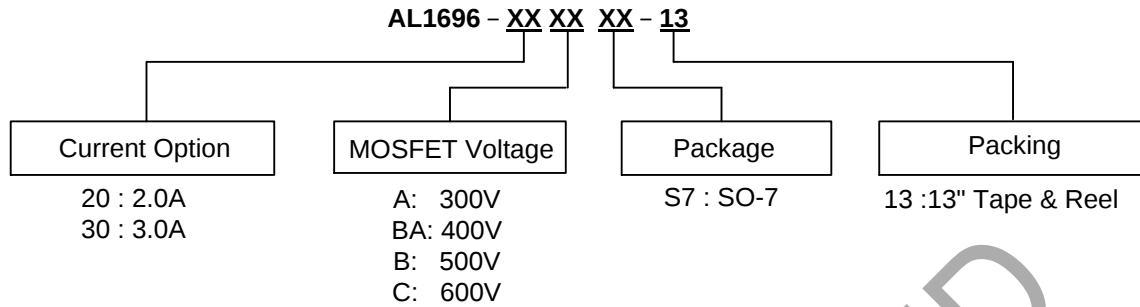
Figure 2. LED Driver Schematic with Passive Bleeder

The passive bleeder includes a capacitor ($C2$, in hundreds of nF) to provide latching current and a resistor ($R1$) to limit the current spike. Because a large $C2$ will affect the PF, THD and efficiency negatively, the value of the capacitor ($C2$) should be selected carefully. Generally, a capacitance from 100nF/400V to 330nF/400V is recommended. $R1$ is used to limit the latching current. If $R1$ is too big, the latching current will be not enough and the TRIAC dimmer will be misfired, resulting in LED flicker. If $R1$ is too small, it will result in greater power dissipation. Generally, a 200Ω to 2kΩ resistor is recommended for $R1$.

Passive Damping Design

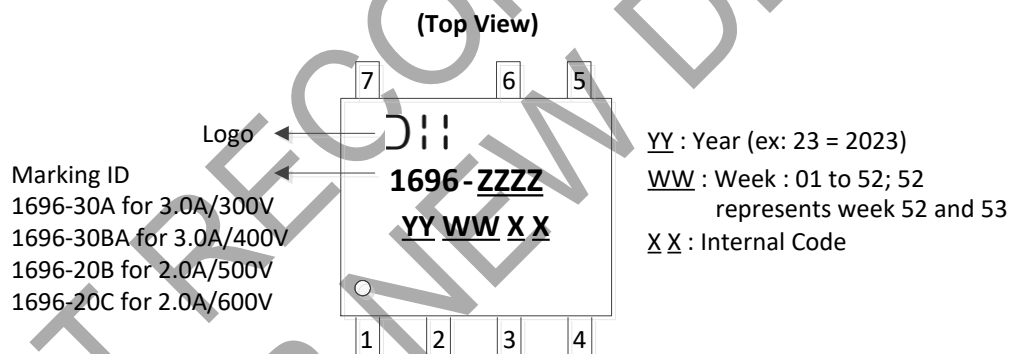
$FR1$ is to limit the spike current caused by quick charging of $C2$ when dimmer on. Normally, $FR1$ will be chosen from 20Ω to 100Ω for low line like 120VAC application, and 51Ω to 200Ω for high line like 230VAC application.

Ordering Information



Part Number	Part Number Suffix	Package Code	Package	Packing	
				Qty.	Carrier
AL1696-30AS7-13	-13	S7	SO-7	4000	Tape & Reel
AL1696-30BAS7-13	-13	S7	SO-7	4000	Tape & Reel
AL1696-20BS7-13	-13	S7	SO-7	4000	Tape & Reel
AL1696-20CS7-13	-13	S7	SO-7	4000	Tape & Reel

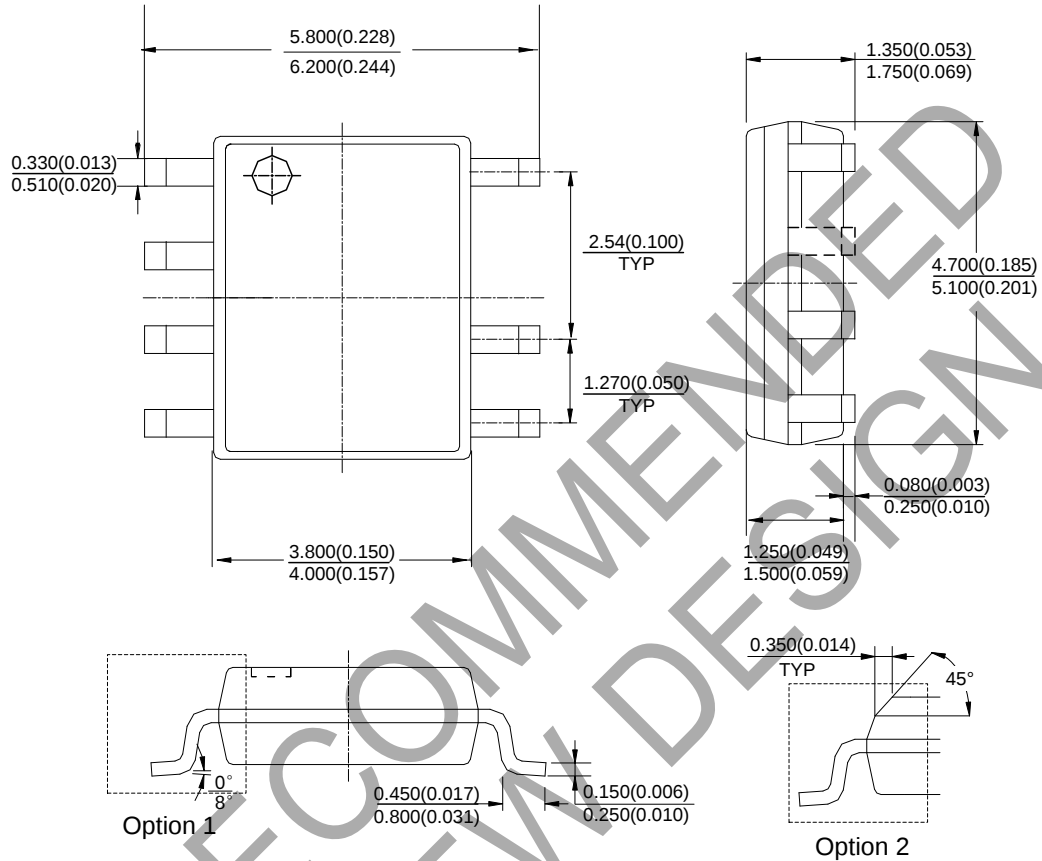
Marking Information



Package Outline Dimensions (All dimensions in mm(inch))

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

(1) Package Type: SO-7

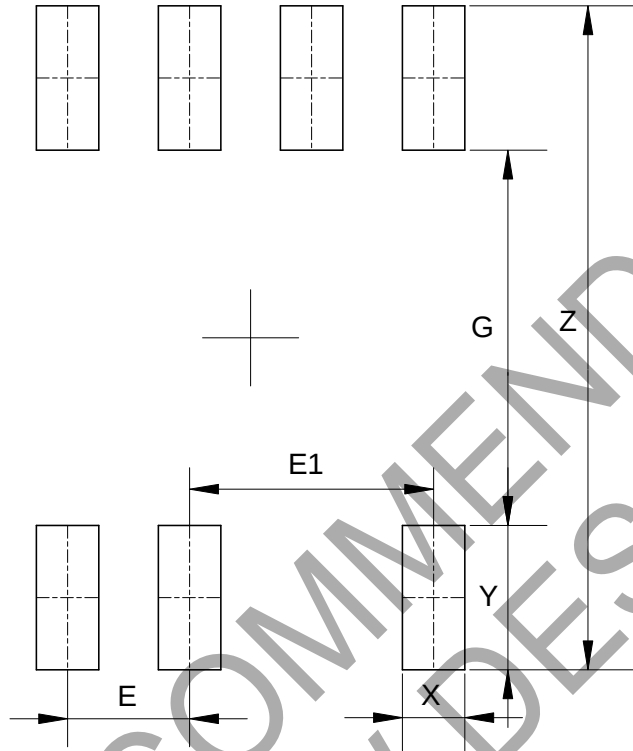


Note: Eject hole, oriented hole and mold mark is optional.

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

(1) Package Type: SO-7



Dimensions	Z (mm)/(inch)	G (mm)/(inch)	X (mm)/(inch)	Y (mm)/(inch)	E (mm)/(inch)	E1 (mm)/(inch)
Value	6.900/0.272	3.900/0.154	0.650/0.026	1.500/0.059	1.270/0.050	2.540/0.100

IMPORTANT NOTICE

1. DIODES INCORPORATED (Diodes) AND ITS SUBSIDIARIES MAKE NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO ANY INFORMATION CONTAINED IN THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).
2. The Information contained herein is for informational purpose only and is provided only to illustrate the operation of Diodes' products described herein and application examples. Diodes does not assume any liability arising out of the application or use of this document or any product described herein. This document is intended for skilled and technically trained engineering customers and users who design with Diodes' products. Diodes' products may be used to facilitate safety-related applications; however, in all instances customers and users are responsible for (a) selecting the appropriate Diodes products for their applications, (b) evaluating the suitability of Diodes' products for their intended applications, (c) ensuring their applications, which incorporate Diodes' products, comply the applicable legal and regulatory requirements as well as safety and functional-safety related standards, and (d) ensuring they design with appropriate safeguards (including testing, validation, quality control techniques, redundancy, malfunction prevention, and appropriate treatment for aging degradation) to minimize the risks associated with their applications.
3. Diodes assumes no liability for any application-related information, support, assistance or feedback that may be provided by Diodes from time to time. Any customer or user of this document or products described herein will assume all risks and liabilities associated with such use, and will hold Diodes and all companies whose products are represented herein or on Diodes' websites, harmless against all damages and liabilities.
4. Products described herein may be covered by one or more United States, international or foreign patents and pending patent applications. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks and trademark applications. Diodes does not convey any license under any of its intellectual property rights or the rights of any third parties (including third parties whose products and services may be described in this document or on Diodes' website) under this document.
5. Diodes' products are provided subject to Diodes' Standard Terms and Conditions of Sale (<https://www.diodes.com/about/company/terms-and-conditions/terms-and-conditions-of-sales/>) or other applicable terms. This document does not alter or expand the applicable warranties provided by Diodes. Diodes does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel.
6. Diodes' products and technology may not be used for or incorporated into any products or systems whose manufacture, use or sale is prohibited under any applicable laws and regulations. Should customers or users use Diodes' products in contravention of any applicable laws or regulations, or for any unintended or unauthorized application, customers and users will (a) be solely responsible for any damages, losses or penalties arising in connection therewith or as a result thereof, and (b) indemnify and hold Diodes and its representatives and agents harmless against any and all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim relating to any noncompliance with the applicable laws and regulations, as well as any unintended or unauthorized application.
7. While efforts have been made to ensure the information contained in this document is accurate, complete and current, it may contain technical inaccuracies, omissions and typographical errors. Diodes does not warrant that information contained in this document is error-free and Diodes is under no obligation to update or otherwise correct this information. Notwithstanding the foregoing, Diodes reserves the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes.
8. Any unauthorized copying, modification, distribution, transmission, display or other use of this document (or any portion hereof) is prohibited. Diodes assumes no responsibility for any losses incurred by the customers or users or any third parties arising from any such unauthorized use.
9. This Notice may be periodically updated with the most recent version available at <https://www.diodes.com/about/company/terms-and-conditions/important-notice>

The Diodes logo is a registered trademark of Diodes Incorporated in the United States and other countries.
All other trademarks are the property of their respective owners.
© 2023 Diodes Incorporated. All Rights Reserved.

www.diodes.com